

# SOT829-1

plastic thin fine-pitch ball grid array package; 256 balls; body  
11 x 11 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

|                                |                                         |
|--------------------------------|-----------------------------------------|
| Terminal position code         | B (bottom)                              |
| Package type descriptive code  | TFBGA256                                |
| Package type industry code     | TFBGA256                                |
| Package style descriptive code | TFBGA (thin fine-pitch ball grid array) |
| Package style suffix code      | NA (not applicable)                     |
| Package body material type     | P (plastic)                             |
| JEDEC package outline code     | MO-195                                  |
| Mounting method type           | S (surface mount)                       |
| Issue date                     | 25-9-2003                               |

Table 1. Package summary

| Symbol         | Parameter                      |  | Min   | Typ | Nom | Max  | Unit |
|----------------|--------------------------------|--|-------|-----|-----|------|------|
| D              | package length                 |  | 10.9  | -   | 11  | 11.1 | mm   |
| E              | package width                  |  | 10.9  | -   | 11  | 11.1 | mm   |
| A              | seated height                  |  | [tbd] | -   | 1.1 | 1.1  | mm   |
| A <sub>2</sub> | package height                 |  | 0.75  | -   | 0.8 | 0.85 | mm   |
| n <sub>2</sub> | actual quantity of termination |  | -     | -   | 256 | -    |      |

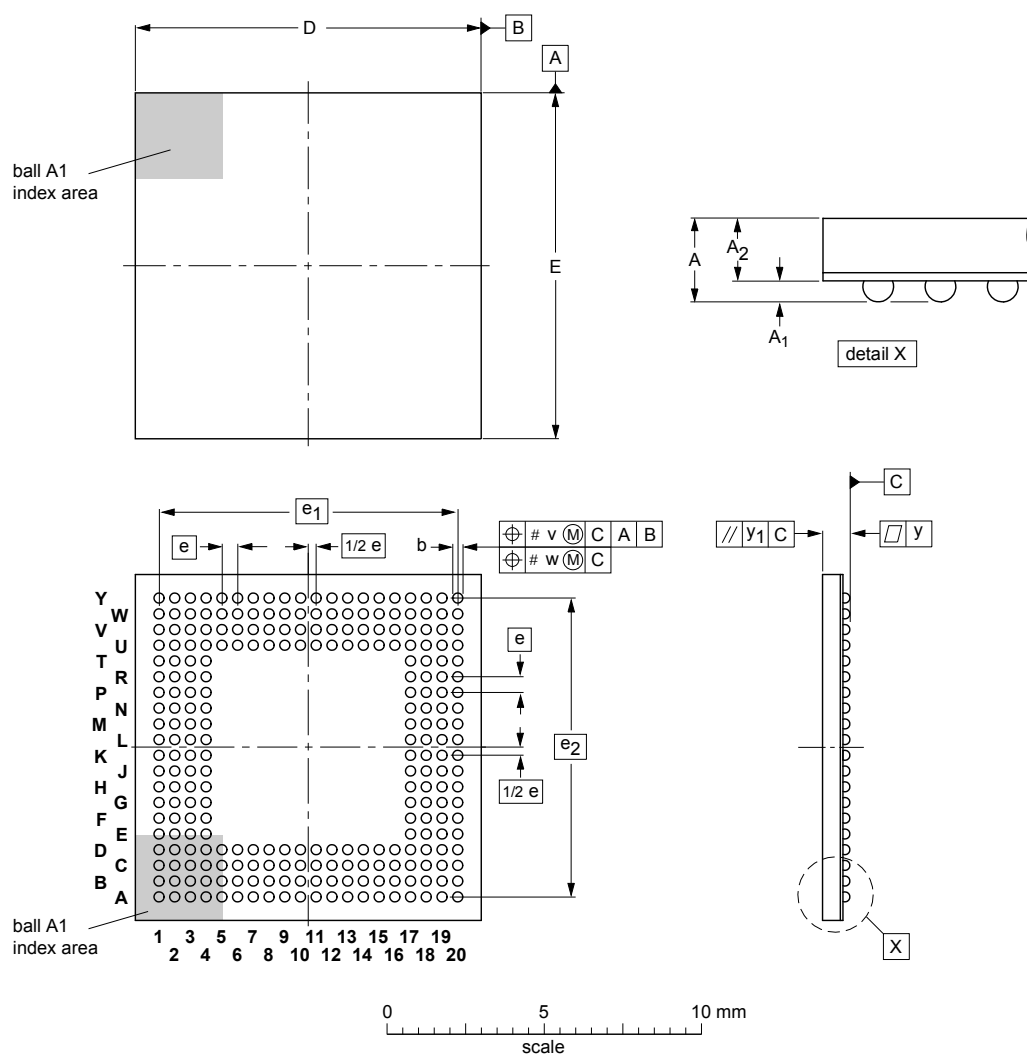


**plastic thin fine-pitch ball grid array package; 256 balls; body 11 x 11 x 0.8 mm**

## 2. Package outline

**TFBGA256:** plastic thin fine-pitch ball grid array package; 256 balls; body 11 x 11 x 0.8 mm

**SOT829-1**



**Fig. 1. Package outline TFBGA256 (SOT829-1)**

3. Soldering

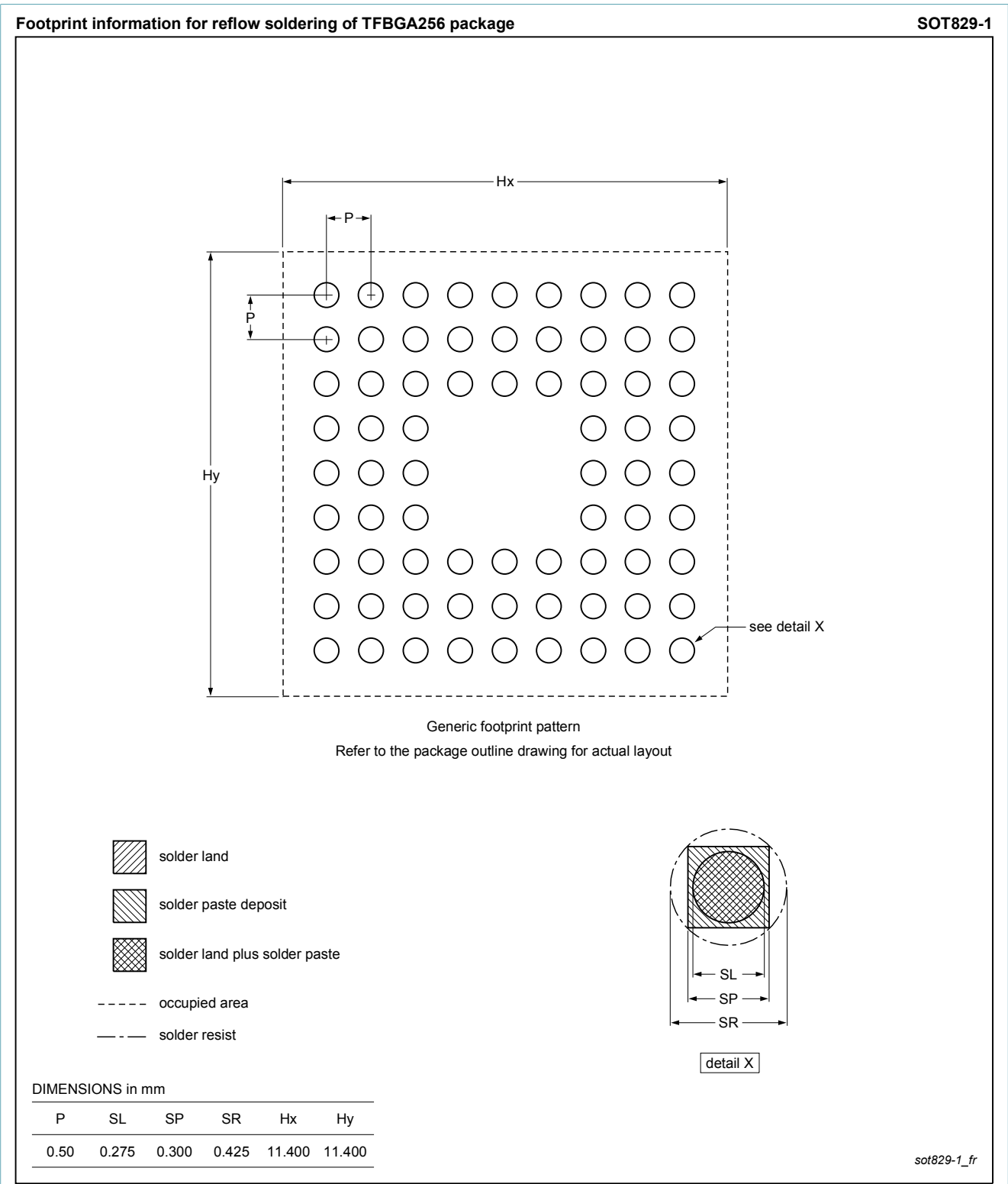


Fig. 2. Reflow soldering footprint for TFBGA256 (SOT829-1)

## 4. Legal information

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Date of release: 8 February 2016